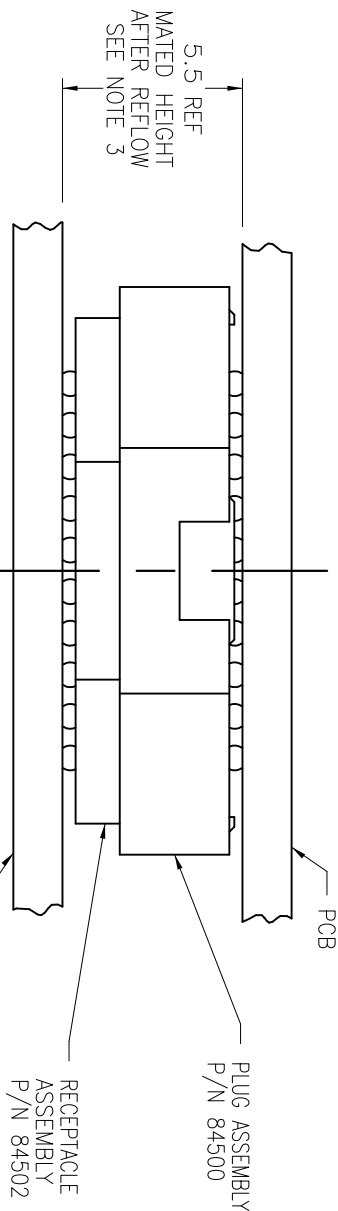


PRODUCT NUMBER

SEE TABLE-SHEET 2



MATED HEIGHT AFTER REFLOW IS BASED ON Ø.64mm PAD (METAL-DEFINED) AND 42mm COINED PASTE STENCIL THICKNESS. SEE NOTE 7.

AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW – MATED CONNECTORS

NOTES:

- ① MATERIAL:

HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING:

CONTACT: (SEE TABLE ON SHEET 2)

SOLDER BALL: (SEE TABLE ON SHEET 2)

95.5Sn/4Ag/0.5Cu

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.

3. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.

4. KNIT LINE: SLIGHT VISIBLE MARKS (USUALLY A LINE) INDICATING THE DIRECTION AND MEETING POINT OF PLASTIC RESIN FLOW FRONTS TRAVELING AROUND ANY OBSTRUCTIONS TO THE RESIN FLOW VIA THE REQUIRED MOLD TOOLING.

- 5 FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

- 6) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION.

7. PLATING FOR INDICATED -2XX SERIES PRODUCT NUMBERS MEET THE REQUIREMENTS OF GR-1217-CORE, CENTRAL OFFICE ENVIRONMENT, (25 YEAR LIFE EXPECTANCY), AND INCLUDES SPECIAL CONTACT GEOMETRY.

8. 84502-A01 AND -A01LF ARE CUSTOMER SPECIALS
9. CURRENT COMPANY LOGO TO BE VISIBLE IN APPROXIMATE AREA SHOWN.

10. A  SYMBOL WILL BE NEXT TO ANY DIMENSION, NEW VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION

[illegible]

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